Parker – Engineered Materials Group

ENGINEERING YOUR SUCCESS.



Parker at a Glance



We are a global business with a local focus.



Footprint of a Global Leader

Divisions

Assembly and Protection Solutions Division Chomerics Division Composite Sealing Systems Division Elastomer Process Materials Division Engineered Polymer Systems Division Latin America Division Noise Vibration and Harshness Division O-Ring and Engineered Seals Division Prädifa Technology Division Sealing Technologies Asia Division

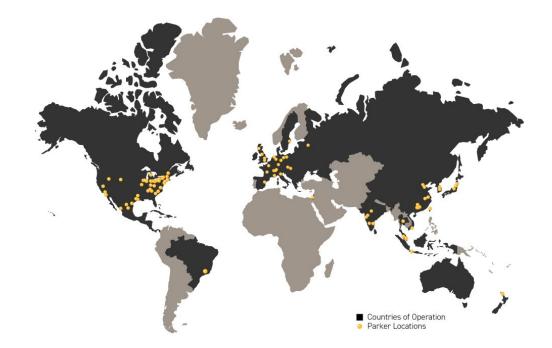
310 Distributors

75 Manufacturing Locations Worldwide

2 13,100 Employees



Serving **63,500** Customers in **32** Countries







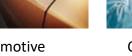
Market Focus



Aerospace









Chemical Industries



Consumer



General Industries



Mobile Industrial



Information Technology



Life Sciences



Military



Oil & Gas



Other Transportation



Power Generation

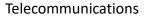


Renewable Energy



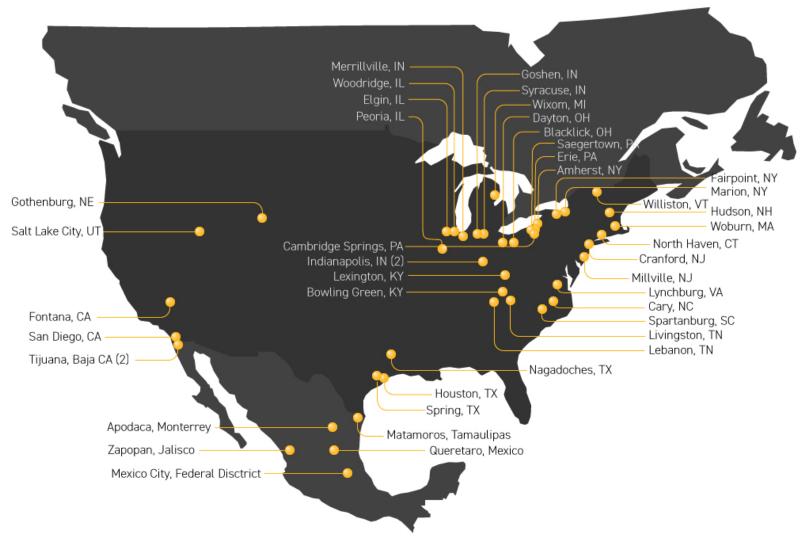
Semiconductor







North America





Parker Chomerics



About Parker Chomerics



Global leader of premier engineered material solutions



Core competencies: Material science and process technology



Market and customer driven new product development



Integrated electronics housings and displays



Custom engineered solutions based on industry expertise



Global supply chain management and manufacturing

Key Technologies

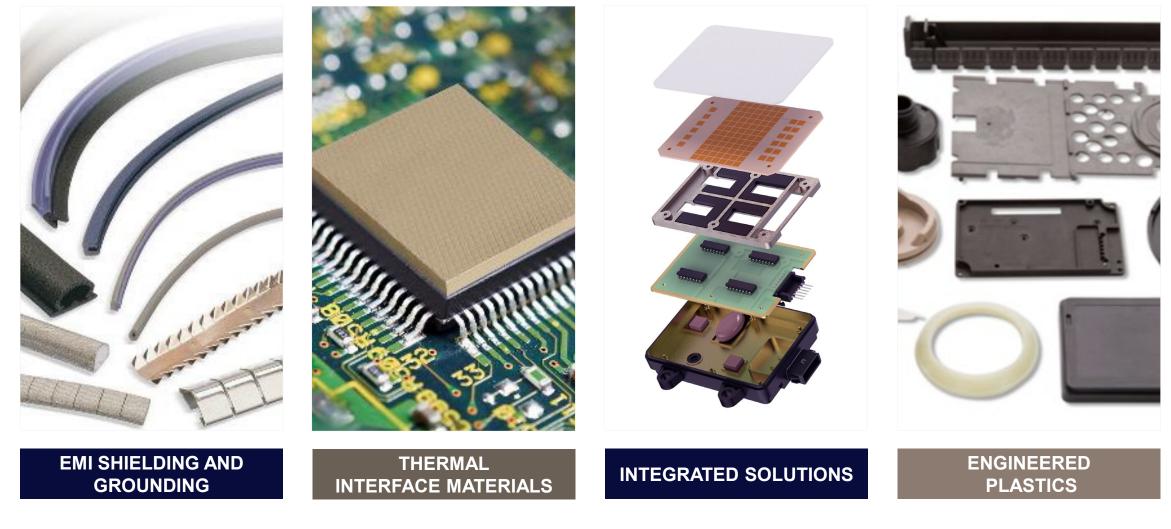
- Integrated Assemblies
- Thermal Management
- Grounding
- Board Level Shielding
- EMI Enclosure Shielding
- Engineered Plastic Solutions
- Optical Display Solutions

Key Markets

- Aerospace
- Automotive
- Consumer Electronics
- Defense
- Industrial
- Information Technology
- Life Science
- Telecommunications

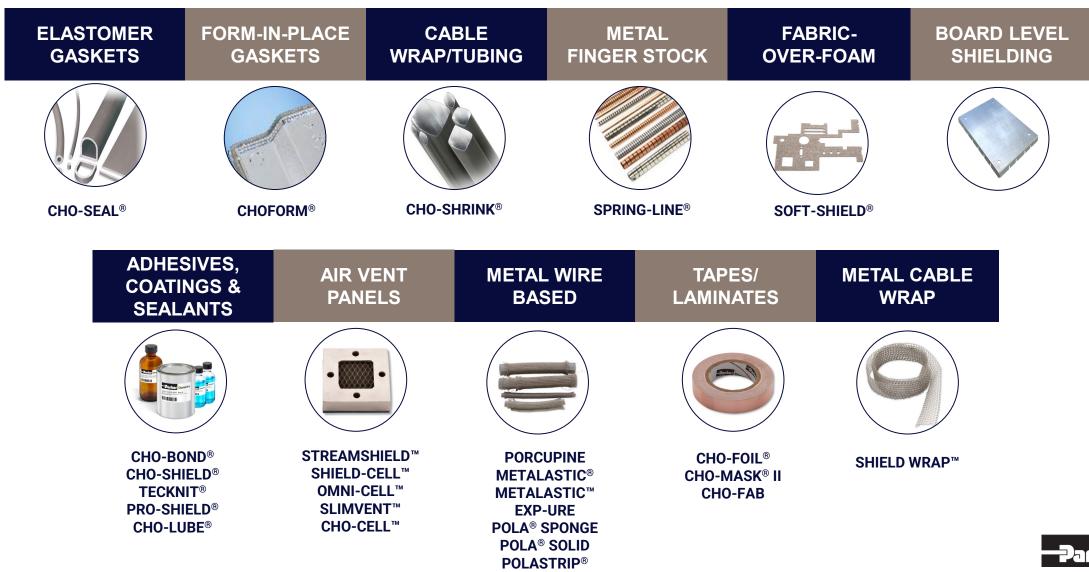


Technology Portfolio

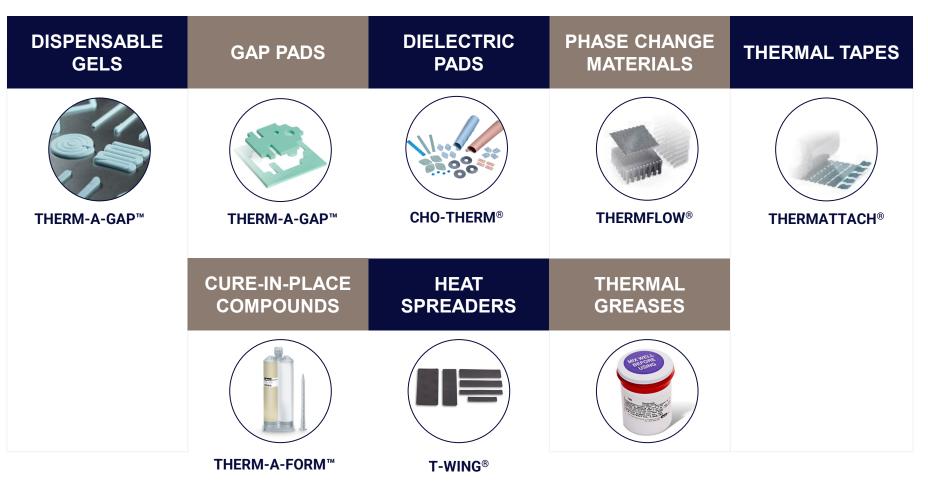




EMI Shielding and Grounding Products



Thermal Interface Products



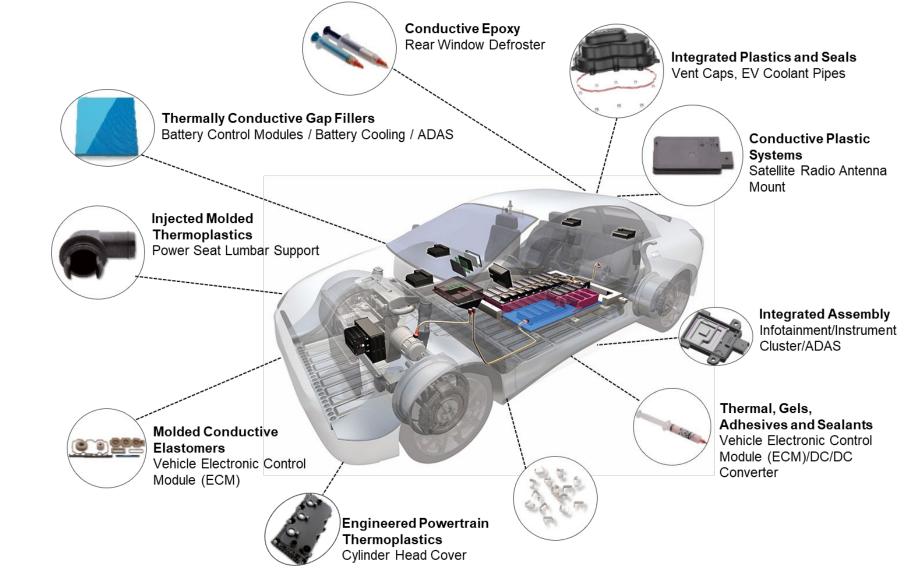


Engineered Plastic Solutions





Automotive Solutions





Parker Sealing Technologies

Products: O-Rings, Gaskets, Lip Seals Compounds: Elastomers, PTFE, Plastics, 2K/3K



Back-up Rings



Flange Seals



Rotary Seals & Bearing Isolators



Buffer Seals



Guiding Elements and **Guiding Tapes**

Static Seals



Cushioning Seals



O-Rings and O-Ring Accessories

Valve Seals





Piston Seals

Custom Seals

2/3K-Parts



Wipers



Fastener Seals

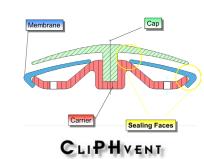
Extruded Profiles







Tolerance **Compensation Seal**





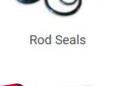
2/3K-Parts



Smart Seals







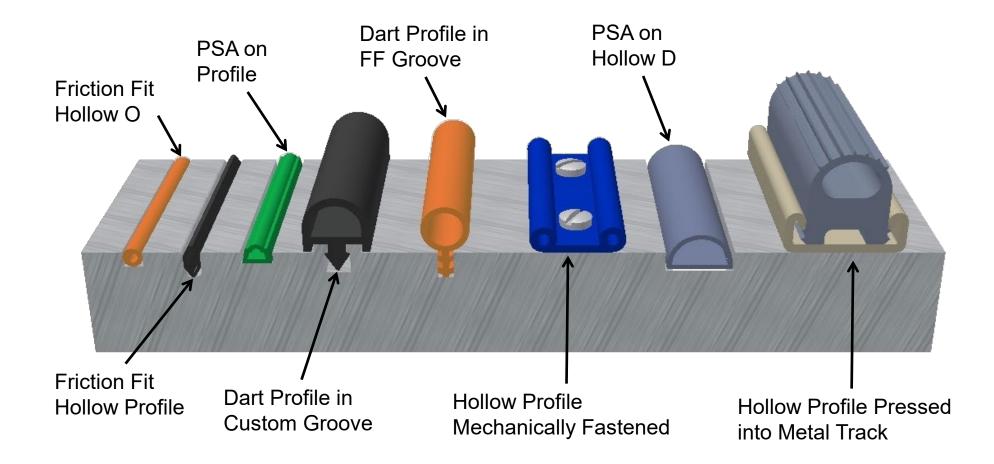
Energized

PTFE





Other Retention Options





Battery Closures, Cooling Systems and HVAC

Cooling systems in electrified systems are some of the most critical parts of a vehicle. Parker provides highly engineered seals that are coolant compatible to ensure that this critical systems operates smoothly.



O-rings Press-in-place seals Thermal gels Molded shapes Integrated seals





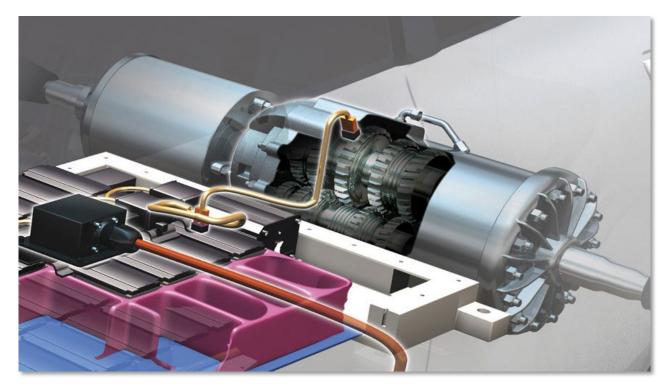


Battery Closure Sealing Plug Under Development Lucid / CHO / OES



Electric Motors

Electrical motors require a variety of static and dynamic seals to seal air and fluids.

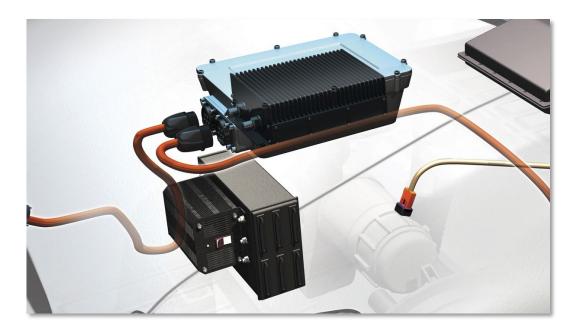


Dust exclusion, bearing isolator seals Press-in-place perimeter seals Radial seals High speed shaft seals



Inverters, Converters, Onboard Chargers

Electrical systems within the vehicle require perimeter seals, port seals, connector seals, EMI shielding and thermal management. Parker can provide all of these solutions.

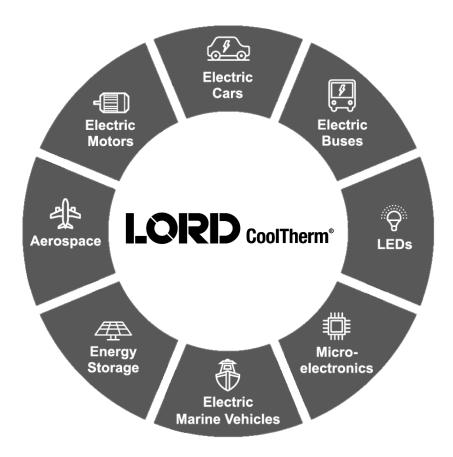


Cooling system O-ring seals Extruded EMI gaskets Liquid silicon rubber perimeter seals Perimeter carrier gaskets Press-in-place perimeter seals Thermal gels Press-in-place coolant seals Press-in-place environment seals Thermal interface materials Custom molded connectors Perimeter seals



Parker APS Division

Our Expertise



Visit us online at www.LORD.com/CoolTherm

Key Markets

- Automotive
- Energy
- Electronics
- Marine
- Industrial
- Aerospace and Defense
- Oil and Gas

Key Products

- Thermal Management/Electronic Materials
- Adhesives and Coatings
- Sensing Systems
- Electro-Mechanical Motion and Vibration Control Systems
- Motion and Vibration Control Assemblies



Electrification Solutions

INFOTAINMENT / NAVIGATION MCU, BOARD / CHIP LEVEL ELECTRONICS

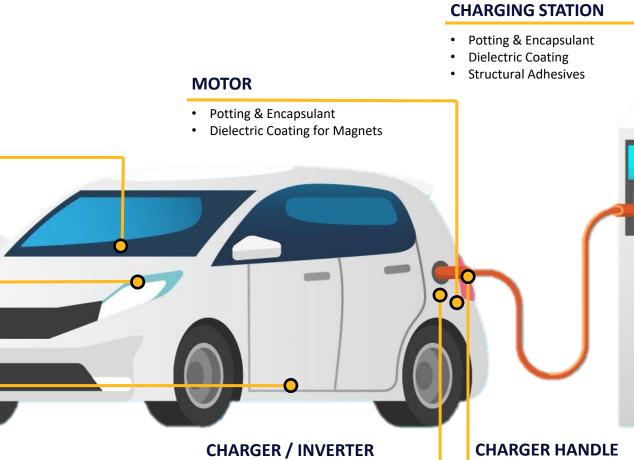
- Potting & Encapsulant
- Thermally Conductive Gap Filler
- Gels, Greases, Underfills
- Thermally and Electrically Conductive Materials

HEADLAMPS

- Potting & Encapsulant
- Thermally Conductive Gap Filler
- Electrically Conductive Adhesive ٠
- Sealants

BATTERY PACK

- Potting & Encapsulant
- Thermally Conductive Gap Filler
- Thermal Adhesives ٠
- Structural Adhesives ٠
- **Dielectric Coatings** ٠
- Low-Density Foams



- Potting & Encapsulant
- Thermally Conductive Gap Filler
- **Dielectric Coating** •

- Potting & Encapsulant
- Structural Adhesives



One Company, Multiple Chemistries

	Silicone	Urethane	Ероху	Acrylic
Properties	Wide temp range, protects fragile electronics	Low temp silicone alternative, good moisture barrier	High adhesion, chemically resistant, rigid	Structural bonding with thermal conductivity
Temperature range	•	Ο	•	0
Delicate electronics	•	•	•	O
Moisture barrier	Ο	•	•	•
Adhesive strength	O	•	•	•
Processing	۲	•	•	•
Chemical resistance	O	•	•	٩
Electrical insulation	•	•	•	•
Repairability	•	•	O	O
Hardness	Low	Medium	High	High

*These values are only applicable to our thermally conductive materials.



Thermal Management Products

KEY PRODUCTS

Potting & Encapsulants



Liquid-dispensed, readily flows into all areas, cures in place

Easily dispensed, encapsulates all surfaces, high thermal conductivity, protects sensitive electronics

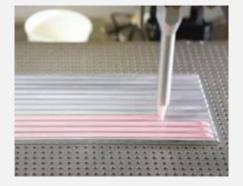
Coatings



Spray applied, cures on the surface

Easily applied, coats metallic surfaces, provides **excellent high voltage insulation**, and provides environmental protection

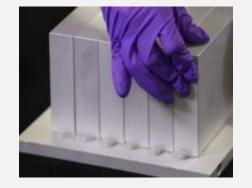




Liquid-dispensed stays in place, cures in place

High-speed dispense, plus high performance thermal conductivity

Adhesives



Liquid-dispensed, stays in place, cures in place

High speed dispense, high thermal conductivity, adds structural adhesion functionality



Applications: Battery Packs

LORD CoolTherm[®] gap fillers, encapsulants, and adhesives act as a thermal link between batteries/modules and a heat sink, ensuring proper heat flow. This easy to dispense, room-temperature cure is fully customizable and compatible with cylindrical, pouch and prismatic batteries.

Gap Filler

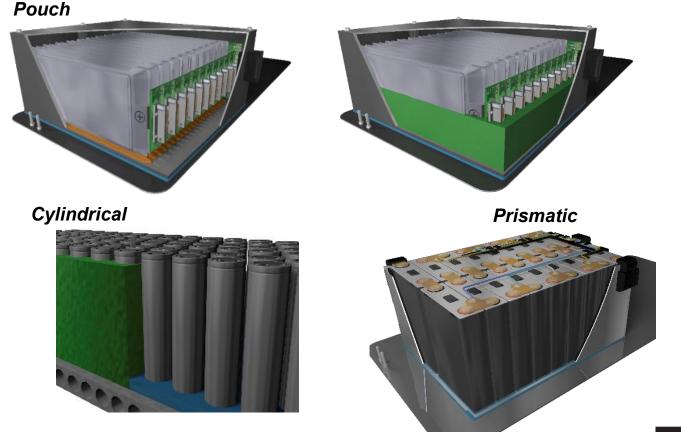
Liquid-dispense, cure in place gap fillers provide low stress on components and improve thermal resistance when compared to thermal pads.

Adhesives

Provide mechanical rigidity and thermal connection where heat is an issue, improving design flexibility by freeing constraints of mechanical fasteners.

Potting & Encapsulation

Facilitate optimum heat transfer due to high thermal conductivity and low viscosity. Ensure even coverage and elimination of all air gaps.

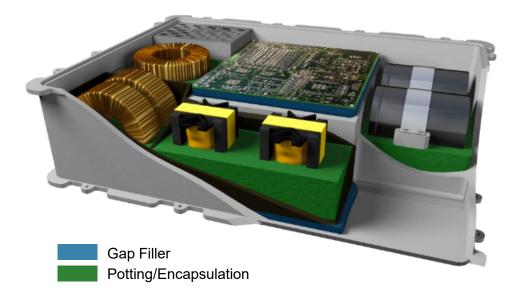




Applications: Charging Systems and Power Electronics

CoolTherm[®] encapsulants and gap fillers enable proper heat flow, resulting in improved thermal performance and lengthened lifespan of parts.

- High thermal conductivity coupled with low viscosity allows for direct connection of the magnetics to the cooling plate.
- Reduce or eliminate inductor hum
- Material quality remains stable over time



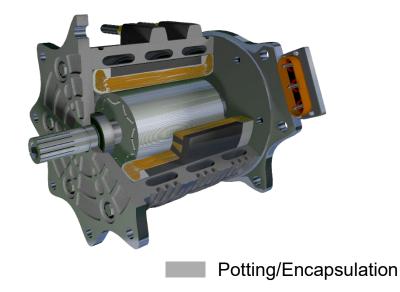




Applications: Motors

CoolTherm[®] potting materials decrease motor operating temperature by up to 50°C and can increase power output by at least 30%

- Relatively low viscosity allows for full impregnation of end windings and stator slots
- Stable to over 200°C
- Material properties do not change within the typical operating temperature of a motor
- Materials survive extended thermal cycling from -40 to 200°C without cracking





Structural Adhesives Products

KEY APPLICATIONS



Body In White



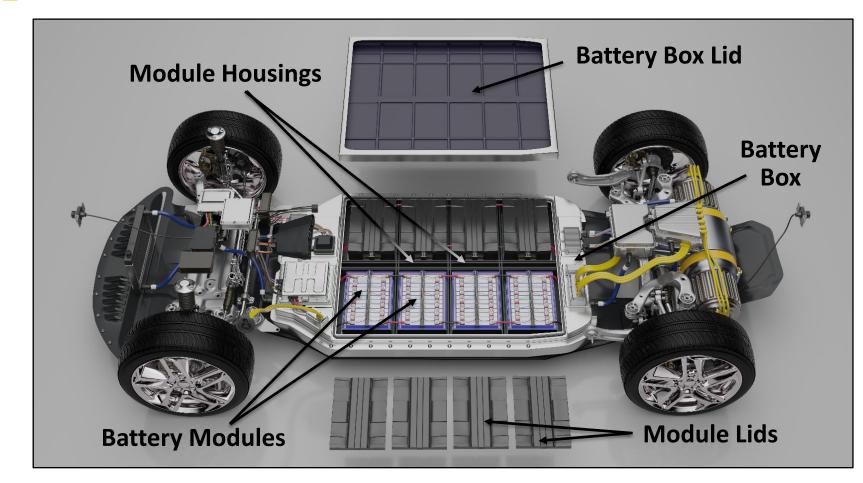
Tailgates, Spoilers



Battery Pack



Typical Modular Battery Pack Design



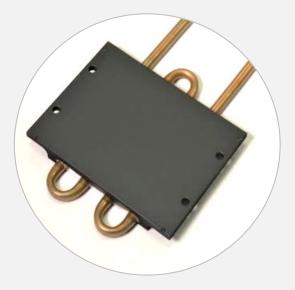
Structural adhesives are used in:

- Module housings
- Cell holders
- Module lids
- Battery box lid attachment and/or sealing
- Various metal-to-metal and metalto-composite assemblies for lightweighting



Coatings and Foaming Products

KEY PRODUCTS



COATINGS ✓ Dielectric insulation



FOAMS I Low density potting (Silicone and Urethane)



Questions?

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